

## Description

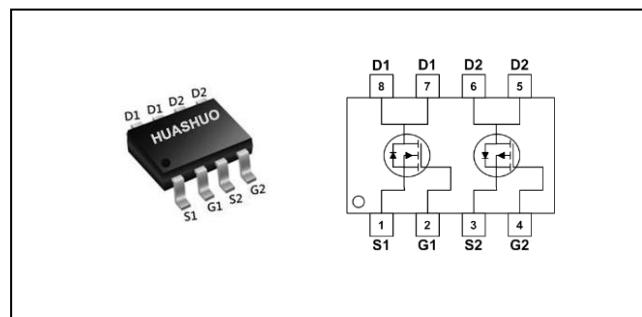
The HSM4606BA uses advanced trench technology and design to provide excellent RDS(ON) with low gate charge. The complementary MOSFETs may be used to form a level shifted high side switch, and for a host of other applications.

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply.

## Product Summary

BVDSS	RDSON	ID
20V	25mΩ	5A
-20V	55mΩ	-5A

## SOP8 Pin Configuration



## Absolute Maximum Ratings

Symbol	Parameter	Rating		Units
		N-Ch	P-Ch	
V <sub>DS</sub>	Drain-Source Voltage	20	-20	V
V <sub>GS</sub>	Gate-Source Voltage	±12	±12	V
I <sub>D</sub> @T <sub>A</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	5	-5	A
I <sub>D</sub> @T <sub>A</sub> =70°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	3.2	-3.2	A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	20	-20	A
P <sub>D</sub> @T <sub>A</sub> =25°C	Total Power Dissipation <sup>4</sup>	2	2	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	-55 to 150	°C

## Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup>	---	63	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>	---	50	°C/W

**N-Channel Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	20	---	---	V
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =4.5V , I <sub>D</sub> =5A	---	25	35	mΩ
		V <sub>GS</sub> =2.5V , I <sub>D</sub> =3A	---	35	45	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	0.5	0.8	1.2	V
△V <sub>GS(th)</sub>	V <sub>GS(th)</sub> Temperature Coefficient		---	-5.08	---	mV/°C
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =16V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =16V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C	---	---	5	
I <sub>GS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±12V , V <sub>DS</sub> =0V	---	---	±100	nA
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =3A	---	8	---	S
Q <sub>g</sub>	Total Gate Charge (4.5V)	V <sub>DS</sub> =10V , V <sub>GS</sub> =4.5V , I <sub>D</sub> =4A	---	4.1	---	nC
Q <sub>gs</sub>	Gate-Source Charge		---	1.2	---	
Q <sub>gd</sub>	Gate-Drain Charge		---	0.8	---	
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> =10V , V <sub>GS</sub> =4.5V , R <sub>G</sub> =3.3Ω I <sub>D</sub> =4A	---	12	---	ns
T <sub>r</sub>	Rise Time		---	9	---	
T <sub>d(off)</sub>	Turn-Off Delay Time		---	33	---	
T <sub>f</sub>	Fall Time		---	6	---	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =10V , V <sub>GS</sub> =0V , f=1MHz	---	400	---	pF
C <sub>oss</sub>	Output Capacitance		---	55	---	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	43	---	

**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>s</sub> =1A , T <sub>J</sub> =25°C	---	---	1	V

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3.The power dissipation is limited by 150°C junction temperature
- 4.The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub> , in real applications , should be limited by total power dissipation.

**P-Channel Electrical Characteristics ( $T_J=25^{\circ}\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}$ , $\text{I}_D=-250\mu\text{A}$	-20	---	---	V
$\text{R}_{\text{DS(ON)}}$	Static Drain-Source On-Resistance <sup>2</sup>	$\text{V}_{\text{GS}}=-4.5\text{V}$ , $\text{I}_D=-5\text{A}$	---	55	65	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=-2.5\text{V}$ , $\text{I}_D=-3\text{A}$	---	65	80	
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	$\text{V}_{\text{GS}}=\text{V}_{\text{DS}}$ , $\text{I}_D = -250\mu\text{A}$	-0.5	-0.7	-1.2	V
$\Delta \text{V}_{\text{GS(th)}}$	$\text{V}_{\text{GS(th)}}$ Temperature Coefficient		---	4.6	---	$\text{mV}/^{\circ}\text{C}$
$\text{I}_{\text{DSS}}$	Drain-Source Leakage Current	$\text{V}_{\text{DS}}=-16\text{V}$ , $\text{V}_{\text{GS}}=0\text{V}$ , $\text{T}_J=25^{\circ}\text{C}$	---	---	-1	$\text{uA}$
		$\text{V}_{\text{DS}}=-16\text{V}$ , $\text{V}_{\text{GS}}=0\text{V}$ , $\text{T}_J=55^{\circ}\text{C}$	---	---	-5	
$\text{I}_{\text{GSS}}$	Gate-Source Leakage Current	$\text{V}_{\text{GS}}=\pm 12\text{V}$ , $\text{V}_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
$\text{g}_{\text{fs}}$	Forward Transconductance	$\text{V}_{\text{DS}}=-5\text{V}$ , $\text{I}_D=-1\text{A}$	---	10	---	S
$\text{Q}_{\text{g}}$	Total Gate Charge (-4.5V)	$\text{V}_{\text{DS}}=-10\text{V}$ , $\text{V}_{\text{GS}}=-4.5\text{V}$ , $\text{I}_D=-3\text{A}$	---	8	---	$\text{nC}$
$\text{Q}_{\text{gs}}$	Gate-Source Charge		---	1.9	---	
$\text{Q}_{\text{gd}}$	Gate-Drain Charge		---	3.1	---	
$\text{T}_{\text{d(on)}}$	Turn-On Delay Time	$\text{V}_{\text{DD}}=-10\text{V}$ , $\text{V}_{\text{GS}}=-4.5\text{V}$ , $\text{R}_G=3.3\Omega$ , $\text{I}_D=-3\text{A}$	---	5.6	---	$\text{ns}$
$\text{T}_{\text{r}}$	Rise Time		---	13	---	
$\text{T}_{\text{d(off)}}$	Turn-Off Delay Time		---	33	---	
$\text{T}_{\text{f}}$	Fall Time		---	11	---	
$\text{C}_{\text{iss}}$	Input Capacitance	$\text{V}_{\text{DS}}=-10\text{V}$ , $\text{V}_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	667	---	$\text{pF}$
$\text{C}_{\text{oss}}$	Output Capacitance		---	134	---	
$\text{C}_{\text{rss}}$	Reverse Transfer Capacitance		---	118	---	

**Diode Characteristics**

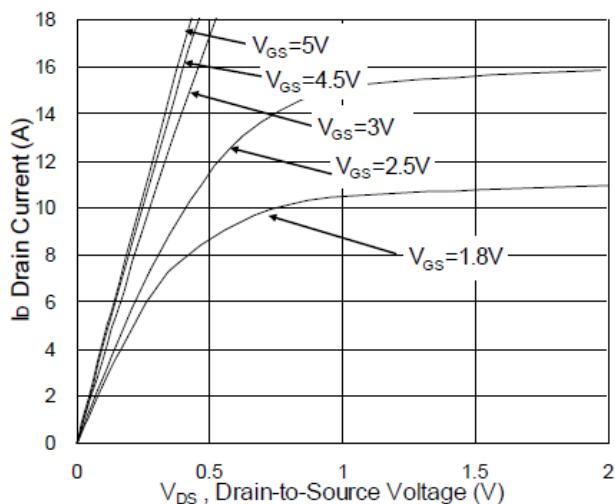
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{V}_{\text{SD}}$	Diode Forward Voltage <sup>2</sup>	$\text{V}_{\text{GS}}=0\text{V}$ , $\text{I}_S=-1\text{A}$ , $\text{T}_J=25^{\circ}\text{C}$	---	---	-1.2	V

Note :

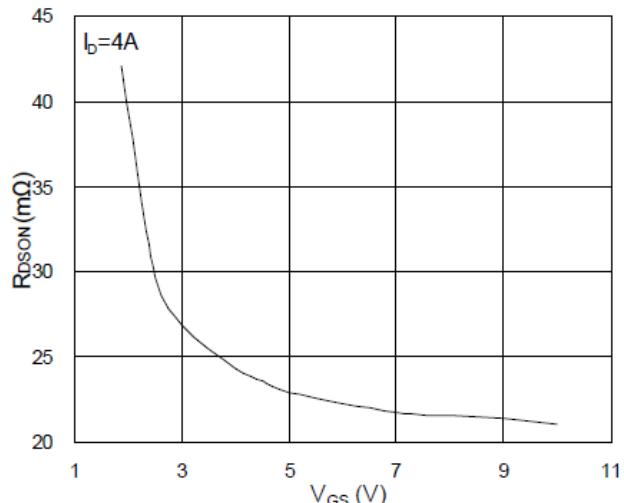
- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\text{us}$  , duty cycle  $\leq 2\%$
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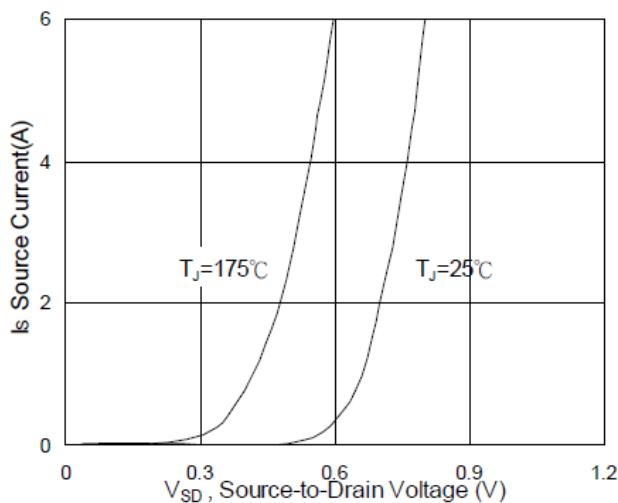
**N-Channel Typical Characteristics**



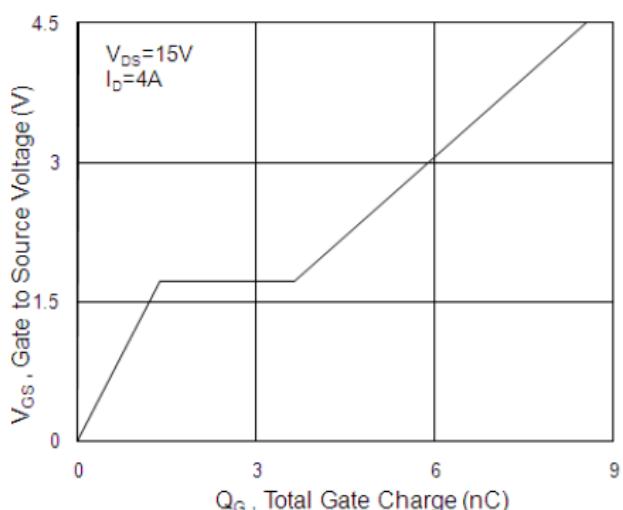
**Fig.1 Typical Output Characteristics**



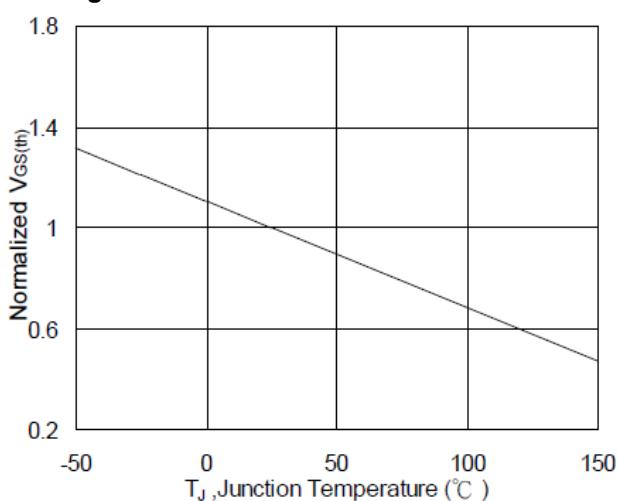
**Fig.2 On-Resistance vs. G-S Voltage**



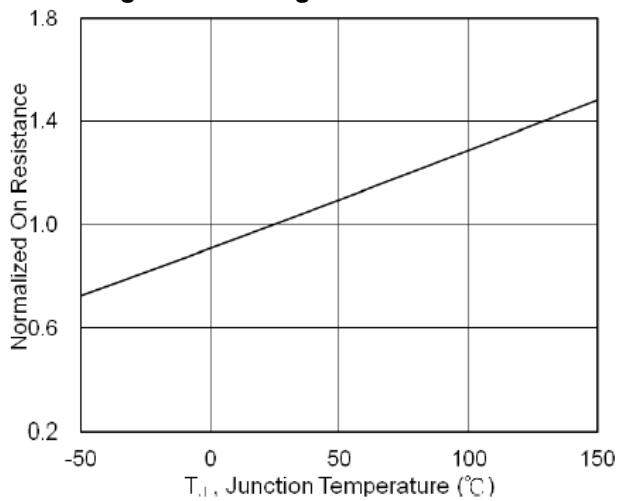
**Fig.3 Forward Characteristics of Reverse**



**Fig.4 Gate-Charge Characteristics**



**Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$**



**Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$**



N-Ch and P-Ch Fast Switching MOSFETs

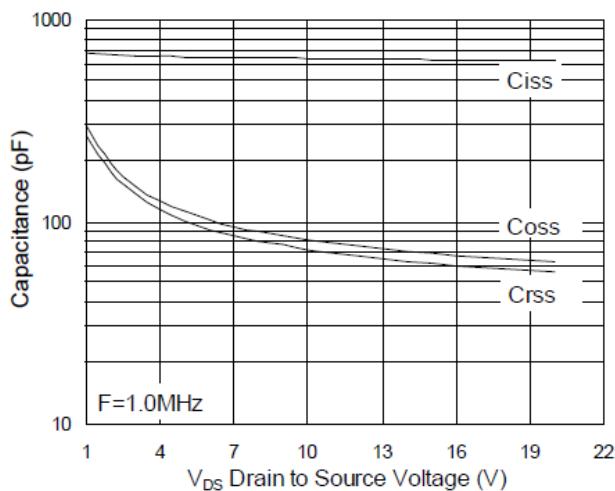


Fig.7 Capacitance

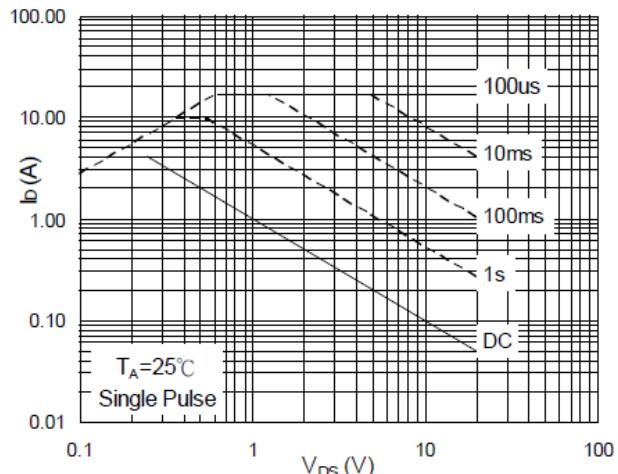


Fig.8 Safe Operating Area

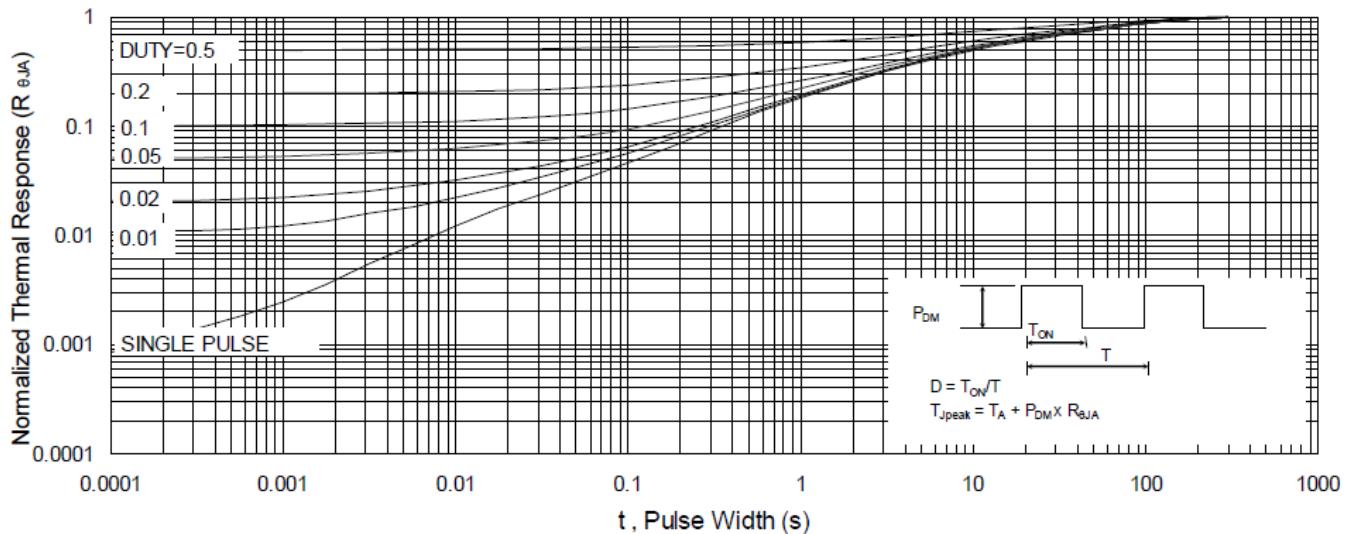


Fig.9 Normalized Maximum Transient Thermal Impedance

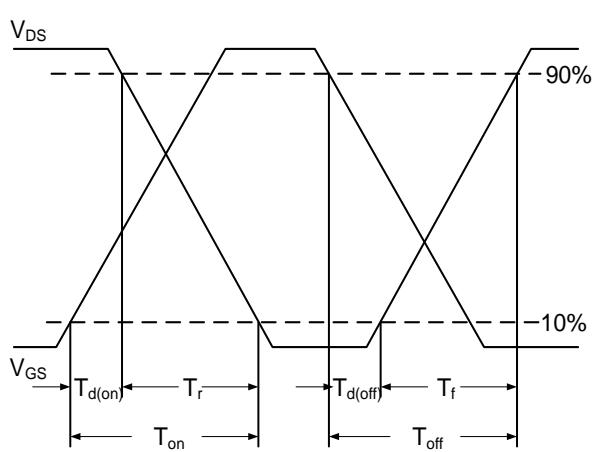


Fig.10 Switching Time Waveform

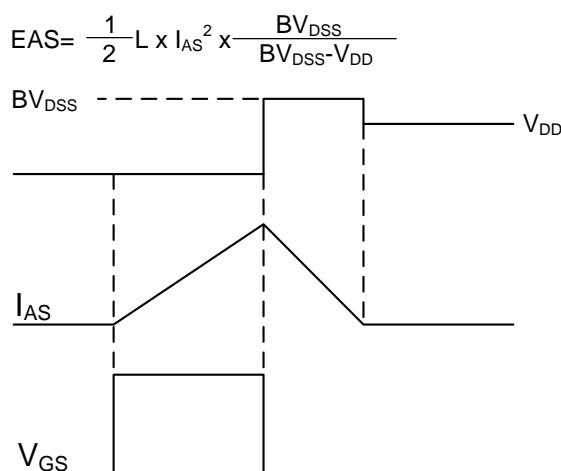


Fig.11 Unclamped Inductive Switching Waveform



**HUASHUO**  
SEMICONDUCTOR

### P-Channel Typical Characteristics

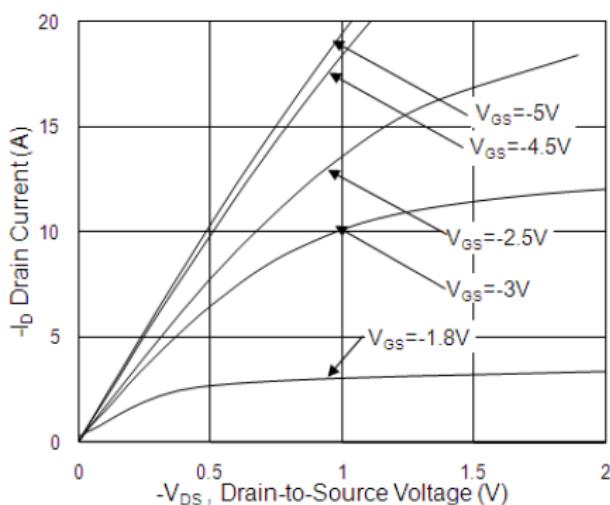


Fig.1 Typical Output Characteristics

**HSM4606BA**

### N-Ch and P-Ch Fast Switching MOSFETs

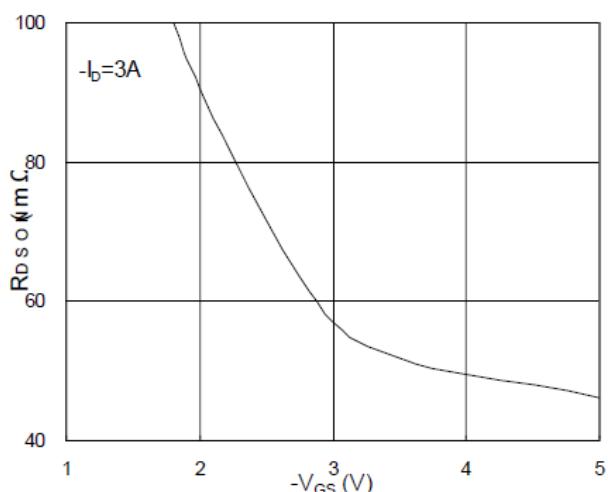


Fig.2 On-Resistance v.s Gate-Source

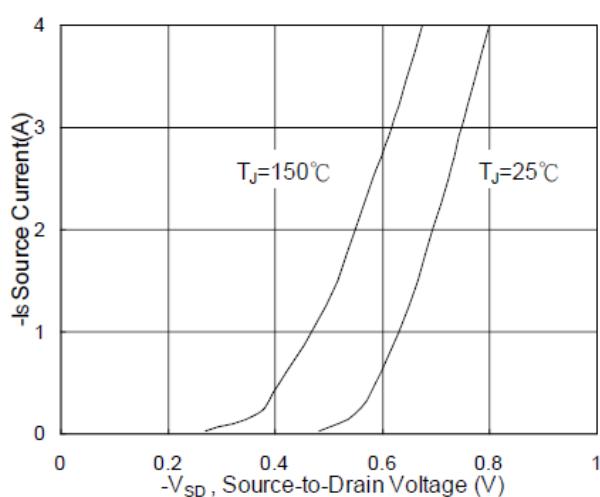


Fig.3 Forward Characteristics of Reverse

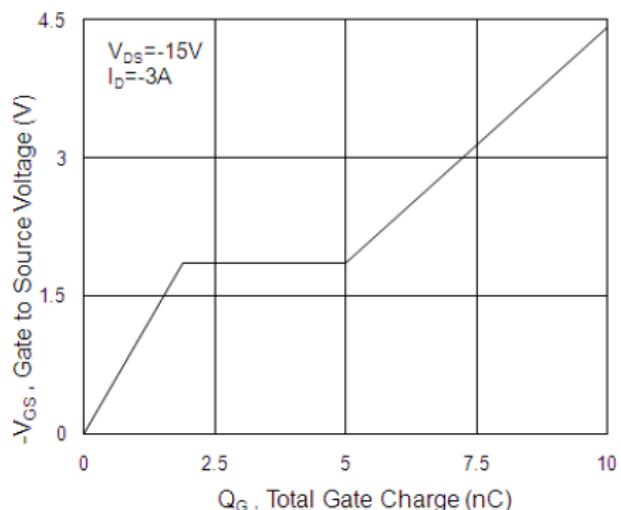


Fig.4 Gate-Charge Characteristics

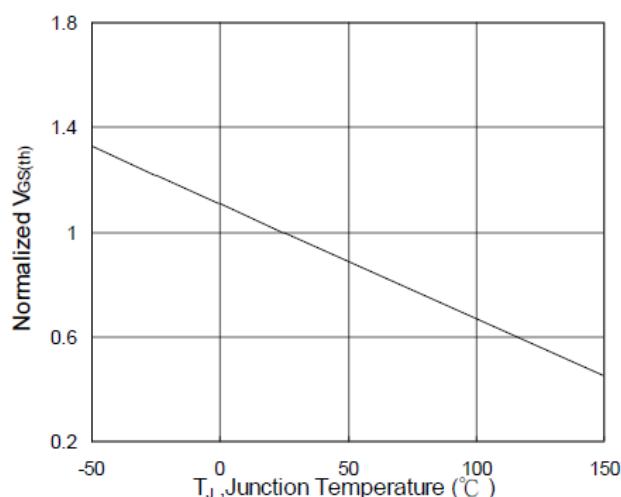


Fig.5 Normalized  $V_{GS(th)}$  v.s  $T_J$

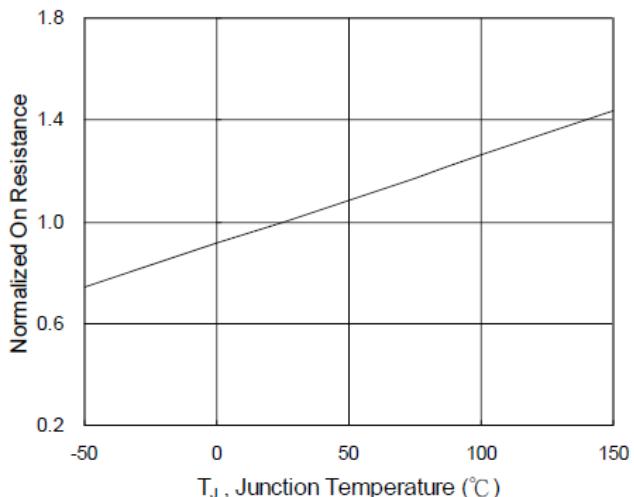


Fig.6 Normalized  $R_{DS(on)}$  v.s  $T_J$

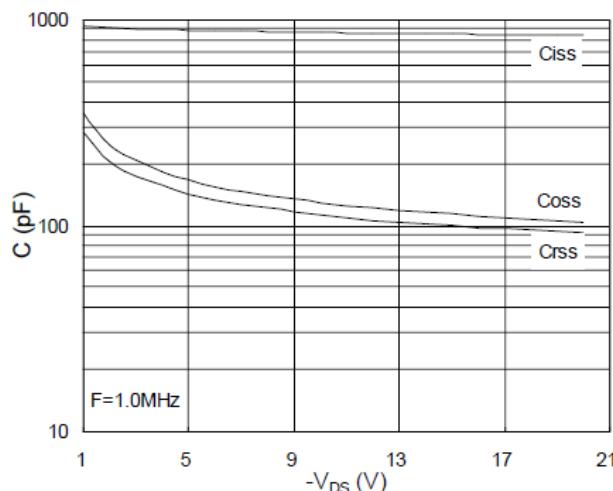


Fig.7 Capacitance

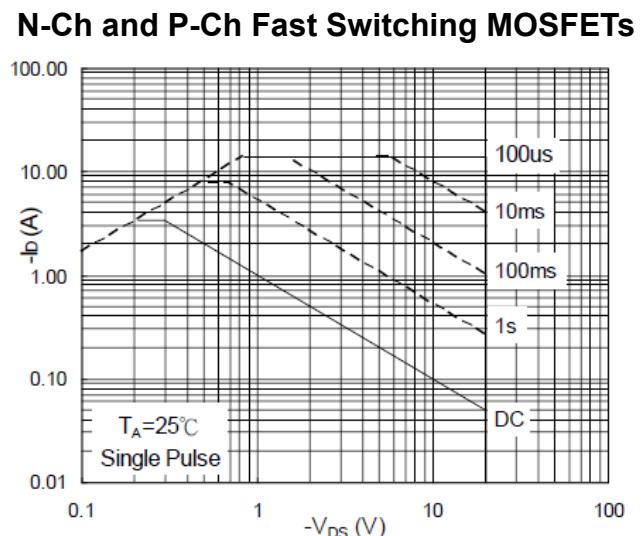


Fig.8 Safe Operating Area

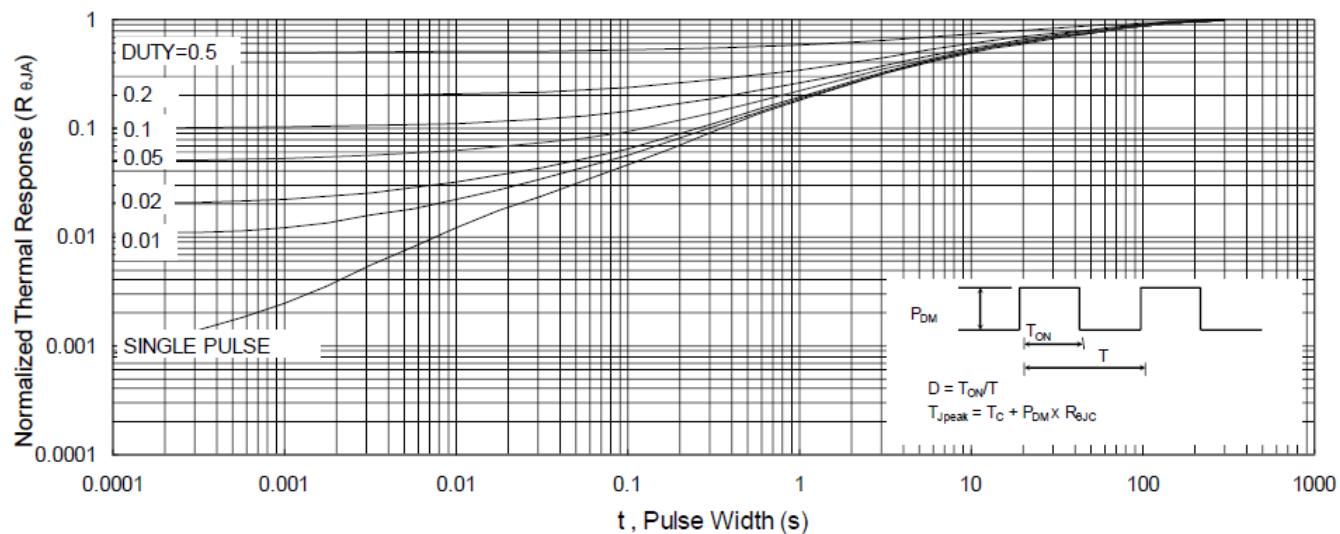


Fig.9 Normalized Maximum Transient Thermal Impedance

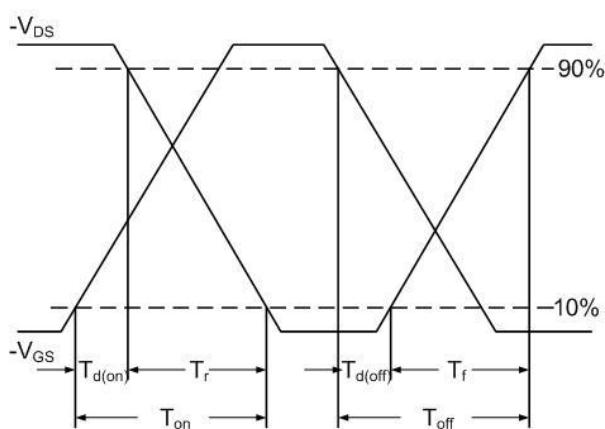


Fig.10 Switching Time Waveform

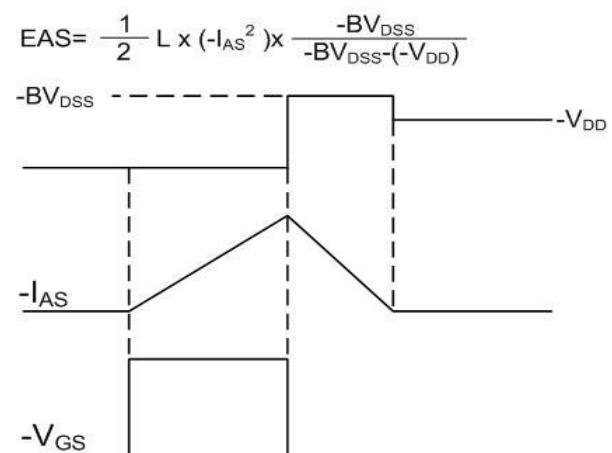


Fig.11 Unclamped Inductive Switching



## Ordering Information

Part Number	Package code	Packaging
HSM4606BA	SOP-8	4000/Tape&Reel

